



Material Content Data Sheet



Sales Product Name		IPD22N08S2L-50		Issued		1. August 2018		
MA#		MA001956354						
Package		PG-TO252-3-11		Weight*		369.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.714	0.46	0.46	4633	4633
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175	
	non noble metal	iron	7439-89-6	0.215	0.06		582	
	non noble metal	copper	7440-50-8	215.017	58.13	58.21	581338	582095
	non noble metal	aluminium	7429-90-5	1.169	0.32	0.32	3162	3162
wire	non noble metal	aluminium	7429-90-5	1.169	0.32	0.32	3162	3162
encapsulation	organic material	carbon black	1333-86-4	1.269	0.34		3432	
	plastics	epoxy resin	-	22.211	6.01		60052	
	inorganic material	silicondioxide	60676-86-0	103.441	27.97	34.32	279671	343155
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10112	10112
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.035	0.01		94	
	noble metal	silver	7440-22-4	0.043	0.01		117	
	non noble metal	lead	7439-92-1	1.652	0.45	0.47	4468	4679
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51850	51918
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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